

## Reverse-Conducting IGBT with monolithic body diode

### Features

- $V_{CE} = 650\text{ V}$
- $I_C = 50\text{ A}$
- Powerful monolithic diode optimized for ZCS applications
- High ruggedness, temperature stable behavior
- Very low  $V_{CEsat}$  and low  $E_{off}$
- Easy paralleling capability due to positive temperature coefficient in  $V_{CEsat}$
- Low EMI
- Low electrical parameters depending (dependence) on temperature
- Qualified according to JESD-022 for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models: <http://www.infineon.com/igbt/>

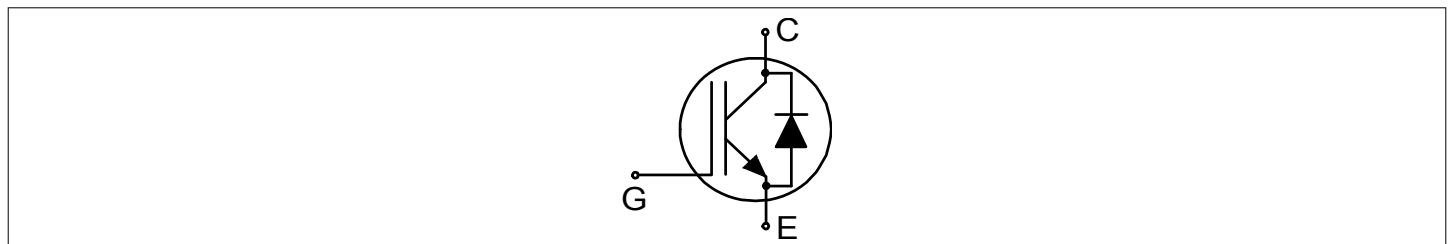
### Potential applications

- Welding
- PFC
- ZCS - converters



- Lead-free
- Green
- Halogen-free
- RoHS

### Description



Type	Package	Marking
IKW50N65WR5	PG-TO247-3	K50EWR5

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## 1 Package

**Table 1** Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Internal emitter inductance measured 5 mm (0.197 in.) from case	$L_E$			13		nH
Storage temperature	$T_{stg}$		-55		150	°C
Soldering temperature	$T_{sold}$	wave soldering 1.6 mm (0.063 in.) from case for 10 s			260	°C
Mounting torque	$M$	M3 screw, Maximum of mounting processes: 3			0.6	Nm
Thermal resistance, junction-ambient	$R_{th(j-a)}$				40	K/W
IGBT thermal resistance, junction-case	$R_{th(j-c)}$				0.53	K/W
Diode thermal resistance, junction-case	$R_{th(j-c)}$				2.29	K/W

## 2 IGBT

**Table 2** Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit	
Collector-emitter voltage	$V_{CE}$	$T_{vj} \geq 25\text{ °C}$	650	V	
DC collector current, limited by $T_{vjmax}$	$I_C$	limited by bondwire	$T_c = 25\text{ °C}$	80	A
			$T_c = 130\text{ °C}$	50	
Pulsed collector current, $t_p$ limited by $T_{vjmax}$	$I_{Cpulse}$		150	A	
Turn-off safe operating area		$V_{CE} \leq 650\text{ V}, T_{vj} \leq 175\text{ °C}$	150	A	
Gate-emitter voltage	$V_{GE}$		±20	V	
Transient gate-emitter voltage	$V_{GE}$	$t_p \leq 10\text{ }\mu\text{s}, D < 0.01$	±30	V	
Power dissipation	$P_{tot}$		$T_c = 25\text{ °C}$	282	W
			$T_c = 100\text{ °C}$	141	

**Table 3** Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Collector-emitter breakdown voltage	$V_{BRCES}$	$I_C = 0.2 \text{ mA}, V_{GE} = 0 \text{ V}$	650			V
Collector-emitter saturation voltage	$V_{CESat}$	$I_C = 50 \text{ A}, V_{GE} = 15 \text{ V}$	$T_{vj} = 25 \text{ }^\circ\text{C}$	1.4	1.8	V
			$T_{vj} = 175 \text{ }^\circ\text{C}$	1.65		
Gate-emitter threshold voltage	$V_{GETh}$	$I_C = 0.5 \text{ mA}, V_{CE} = V_{GE}$	3.2	4	4.8	V
Zero gate-voltage collector current	$I_{CES}$	$V_{CE} = 650 \text{ V}, V_{GE} = 0 \text{ V}$			40	$\mu\text{A}$
Gate-emitter leakage current	$I_{GES}$	$V_{CE} = 0 \text{ V}, V_{GE} = 20 \text{ V}$			100	nA
Transconductance	$g_{fs}$	$I_C = 50 \text{ A}, V_{CE} = 20 \text{ V}$		65		S
Input capacitance	$C_{ies}$	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1000 \text{ kHz}$		6140		pF
Output capacitance	$C_{oes}$	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1000 \text{ kHz}$		55		pF
Reverse transfer capacitance	$C_{res}$	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1000 \text{ kHz}$		23		pF
Gate charge	$Q_G$	$V_{CC} = 520 \text{ V}, I_C = 50 \text{ A}, V_{GE} = 15 \text{ V}$		230		nC
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 400 \text{ V}, V_{GE} = 0/15 \text{ V},$ $R_{G(on)} = 16 \text{ } \Omega,$ $R_{G(off)} = 16 \text{ } \Omega, L_\sigma = 45 \text{ nH},$ $C_\sigma = 32 \text{ pF}$	$T_{vj} = 25 \text{ }^\circ\text{C},$ $I_C = 25 \text{ A}$	45		ns
			$T_{vj} = 175 \text{ }^\circ\text{C},$ $I_C = 25 \text{ A}$	43		
Rise time (inductive load)	$t_r$	$V_{CC} = 400 \text{ V}, V_{GE} = 0/15 \text{ V},$ $R_{G(on)} = 16 \text{ } \Omega,$ $R_{G(off)} = 16 \text{ } \Omega, L_\sigma = 45 \text{ nH},$ $C_\sigma = 32 \text{ pF}$	$T_{vj} = 25 \text{ }^\circ\text{C},$ $I_C = 25 \text{ A}$	17		ns
			$T_{vj} = 175 \text{ }^\circ\text{C},$ $I_C = 25 \text{ A}$	19		
Turn-off delay time	$t_{d(off)}$	$V_{CC} = 400 \text{ V}, V_{GE} = 0/15 \text{ V},$ $R_{G(on)} = 16 \text{ } \Omega,$ $R_{G(off)} = 16 \text{ } \Omega, L_\sigma = 45 \text{ nH},$ $C_\sigma = 32 \text{ pF}$	$T_{vj} = 25 \text{ }^\circ\text{C},$ $I_C = 25 \text{ A}$	417		ns
			$T_{vj} = 175 \text{ }^\circ\text{C},$ $I_C = 25 \text{ A}$	496		
Fall time (inductive load)	$t_f$	$V_{CC} = 400 \text{ V}, V_{GE} = 0/15 \text{ V},$ $R_{G(on)} = 16 \text{ } \Omega,$ $R_{G(off)} = 16 \text{ } \Omega, L_\sigma = 45 \text{ nH},$ $C_\sigma = 32 \text{ pF}$	$T_{vj} = 25 \text{ }^\circ\text{C},$ $I_C = 25 \text{ A}$	16		ns
			$T_{vj} = 175 \text{ }^\circ\text{C},$ $I_C = 25 \text{ A}$	11		
Turn-on energy	$E_{on}$	$V_{CC} = 400 \text{ V}, V_{GE} = 0/15 \text{ V},$ $R_{G(on)} = 16 \text{ } \Omega,$ $R_{G(off)} = 16 \text{ } \Omega, L_\sigma = 45 \text{ nH},$ $C_\sigma = 32 \text{ pF}$	$T_{vj} = 25 \text{ }^\circ\text{C},$ $I_C = 25 \text{ A}$	0.84		mJ
			$T_{vj} = 175 \text{ }^\circ\text{C},$ $I_C = 25 \text{ A}$	1.04		

(table continues...)

**Table 3 (continued) Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Turn-off energy	$E_{off}$	$V_{CC} = 400\text{ V}, V_{GE} = 0/15\text{ V},$ $R_{G(on)} = 16\ \Omega,$ $R_{G(off)} = 16\ \Omega, L_{\sigma} = 45\text{ nH},$ $C_{\sigma} = 32\text{ pF}$	$T_{vj} = 25\text{ }^{\circ}\text{C},$ $I_C = 25\text{ A}$		0.22		mJ
			$T_{vj} = 175\text{ }^{\circ}\text{C},$ $I_C = 25\text{ A}$		0.32		
Total switching energy	$E_{ts}$	$V_{CC} = 400\text{ V}, V_{GE} = 0/15\text{ V},$ $R_{G(on)} = 16\ \Omega,$ $R_{G(off)} = 16\ \Omega, L_{\sigma} = 45\text{ nH},$ $C_{\sigma} = 32\text{ pF}$	$T_{vj} = 25\text{ }^{\circ}\text{C},$ $I_C = 25\text{ A}$		1.06		mJ
			$T_{vj} = 175\text{ }^{\circ}\text{C},$ $I_C = 25\text{ A}$		1.36		
Operating junction temperature	$T_{vj}$		-40		175	$^{\circ}\text{C}$	

Note: Electrical Characteristic, at  $T_{vj} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified.

### 3 Diode

**Table 4 Maximum rated values**

Parameter	Symbol	Note or test condition	Values	Unit	
Repetitive peak reverse voltage	$V_{RRM}$	$T_{vj} \geq 25\text{ }^{\circ}\text{C}$	650	V	
Diode forward current, limited by $T_{vjmax}$	$I_F$	limited by bondwire	$T_c = 25\text{ }^{\circ}\text{C}$	37	A
			$T_c = 100\text{ }^{\circ}\text{C}$	22	
Diode pulsed current, $t_p$ limited by $T_{vjmax}$	$I_{Fpulse}$		150	A	

**Table 5 Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Diode forward voltage	$V_F$	$I_F = 25\text{ A}$	$T_{vj} = 25\text{ }^{\circ}\text{C}$		1.4	1.9	V
			$T_{vj} = 175\text{ }^{\circ}\text{C}$		1.5		
Diode reverse recovery time	$t_{rr}$	$V_R = 400\text{ V}$	$T_{vj} = 25\text{ }^{\circ}\text{C},$ $I_F = 25\text{ A},$ $-di_F/dt = 900\text{ A}/\mu\text{s}$		110		ns
			$T_{vj} = 175\text{ }^{\circ}\text{C},$ $I_F = 25\text{ A},$ $-di_F/dt = 900\text{ A}/\mu\text{s}$		145		

(table continues...)

**Table 5 (continued) Characteristic values**

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Diode reverse recovery charge	$Q_{rr}$	$V_R = 400\text{ V}$	$T_{vj} = 25\text{ °C},$ $I_F = 25\text{ A},$ $-di_F/dt = 900\text{ A}/\mu\text{s}$		1.8		$\mu\text{C}$
					3.5		
Diode peak reverse recovery current	$I_{rrm}$	$V_R = 400\text{ V}$	$T_{vj} = 25\text{ °C},$ $I_F = 25\text{ A},$ $-di_F/dt = 900\text{ A}/\mu\text{s}$		29		A
					39		
Diode peak rate of fall of reverse recovery current	$di_{rr}/dt$	$V_R = 400\text{ V}$	$T_{vj} = 25\text{ °C},$ $I_F = 25\text{ A},$ $-di_F/dt = 900\text{ A}/\mu\text{s}$		600		$\text{A}/\mu\text{s}$
					1200		
Operating junction temperature	$T_{vj}$			-40		175	$^{\circ}\text{C}$

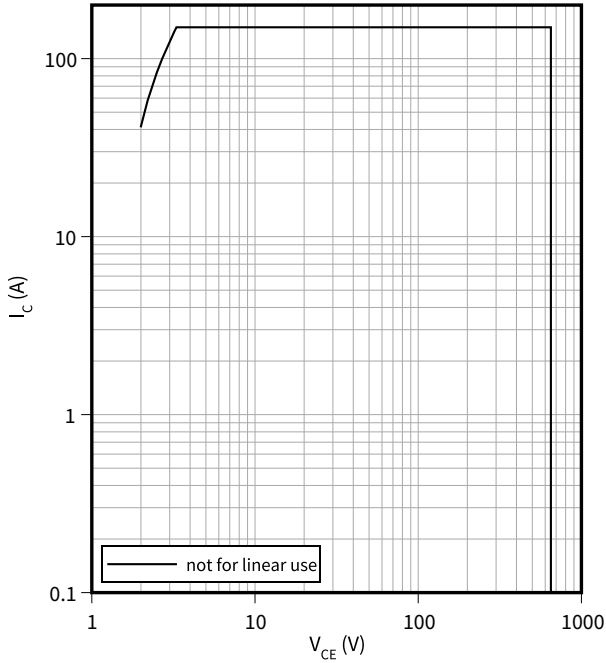
*Note: For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.*

## 4 Characteristics diagrams

### Reverse bias safe operating area

$$I_C = f(V_{CE})$$

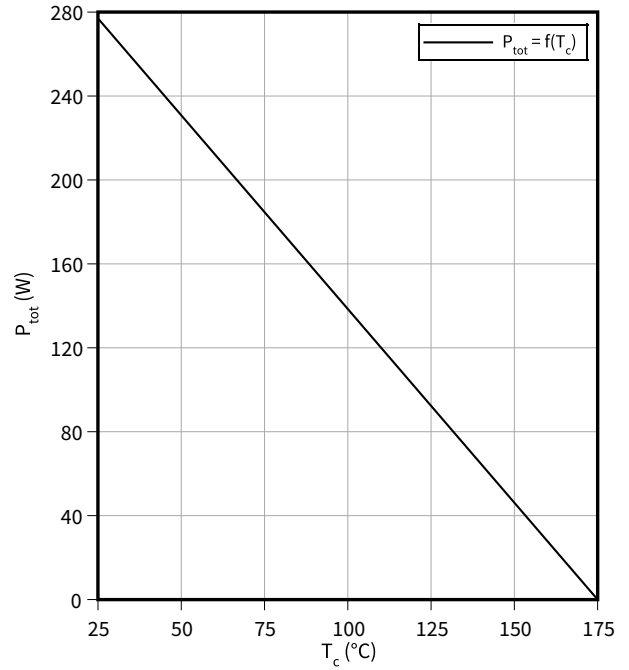
$$T_{vj} \leq 175\text{ °C}, V_{GE} = 15\text{ V}, T_c = 25\text{ °C}$$



### Power dissipation as a function of case temperature

$$P_{tot} = f(T_c)$$

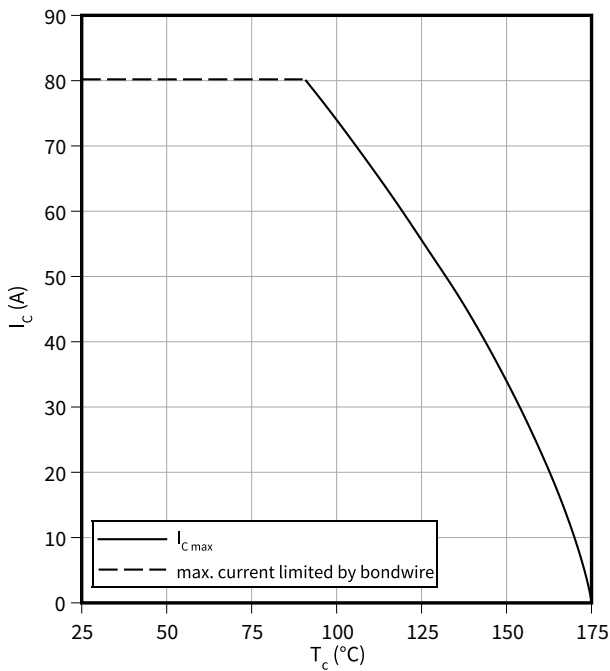
$$T_{vj} \leq 175\text{ °C}$$



### Collector current as a function of case temperature

$$I_C = f(T_c)$$

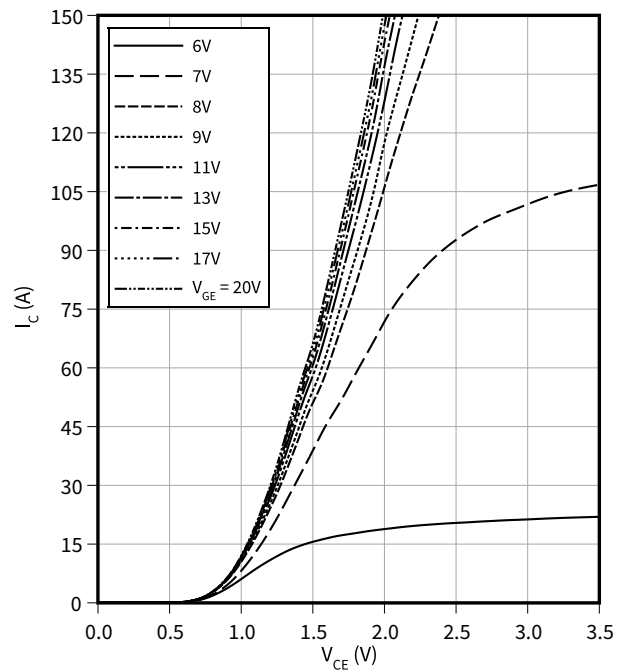
$$T_{vj} \leq 175\text{ °C}, V_{GE} \geq 15\text{ V}$$



### Typical output characteristic

$$I_C = f(V_{CE})$$

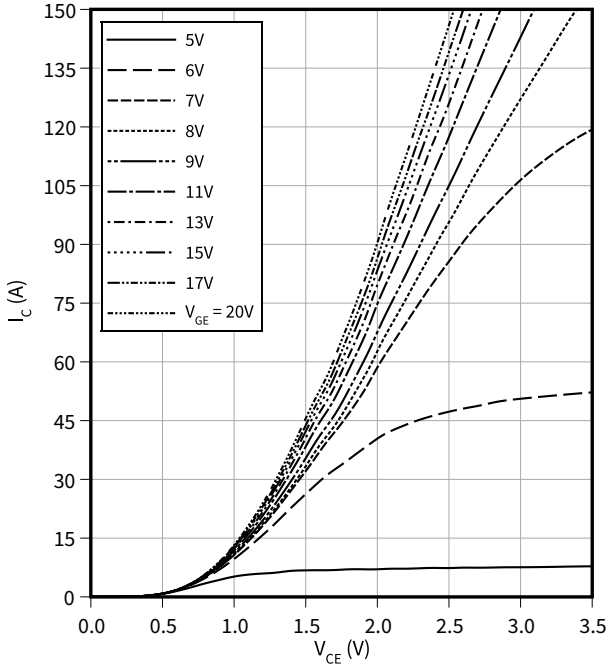
$$T_{vj} = 25\text{ °C}$$



4 Characteristics diagrams

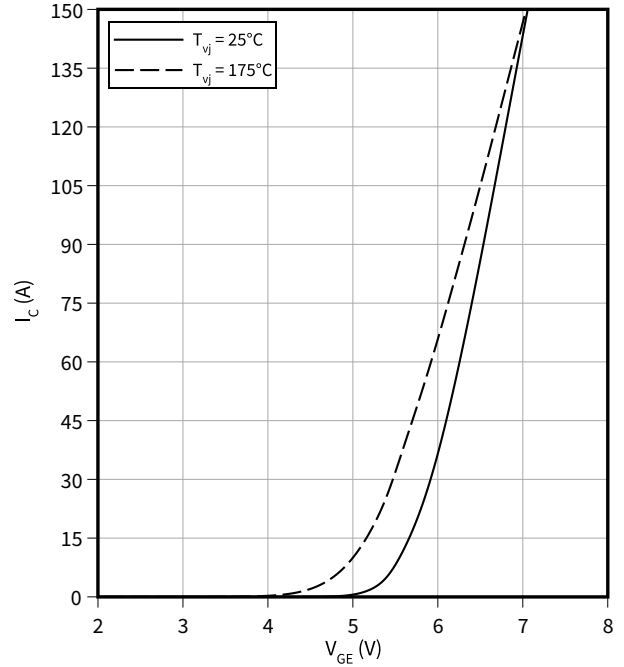
**Typical output characteristic**

$I_C = f(V_{CE})$   
 $T_{vj} = 175\text{ °C}$



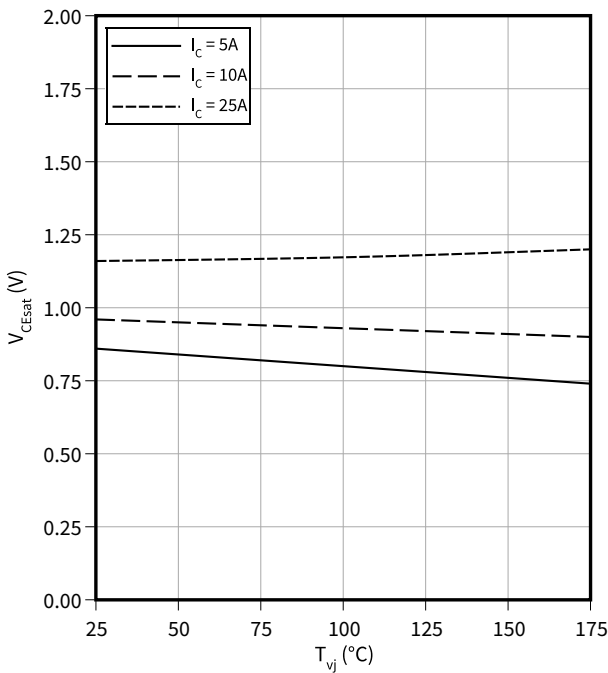
**Typical transfer characteristic**

$I_C = f(V_{GE})$   
 $V_{CE} = 20\text{ V}$



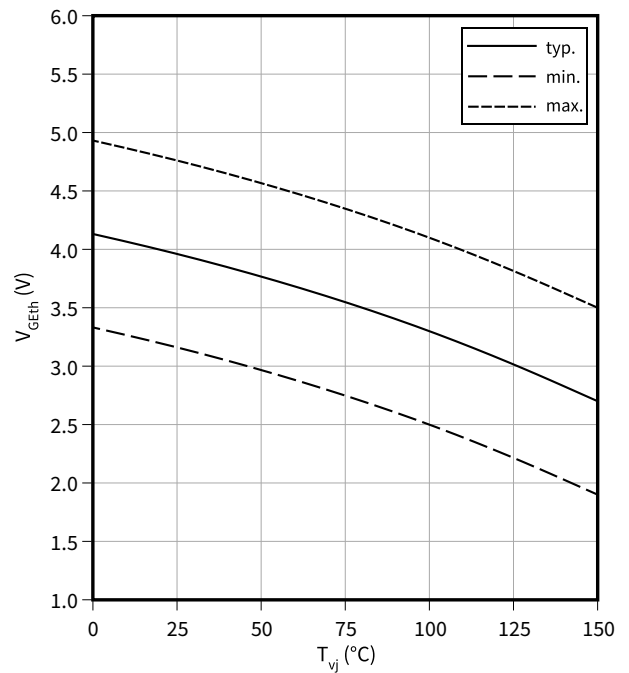
**Typical collector-emitter saturation voltage as a function of junction temperature**

$V_{CEsat} = f(T_{vj})$   
 $V_{GE} = 15\text{ V}$



**Gate-emitter threshold voltage as a function of junction temperature**

$V_{GEth} = f(T_{vj})$   
 $I_C = 0.5\text{ mA}$



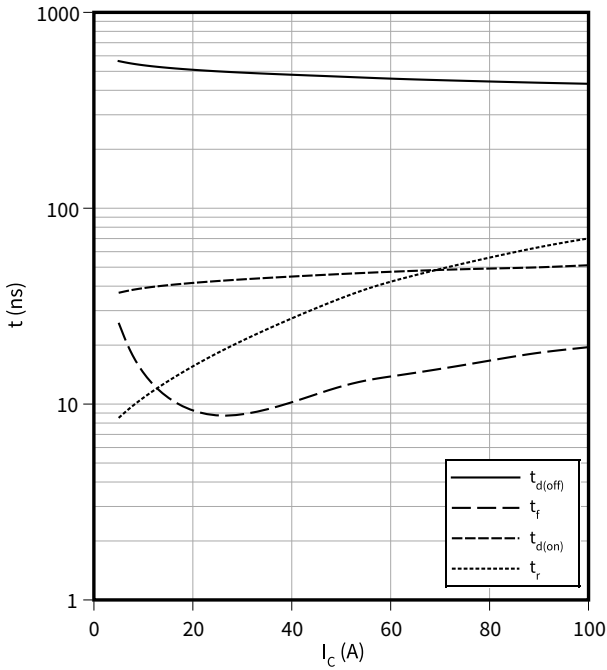


4 Characteristics diagrams

**Typical switching times as a function of collector current**

$t = f(I_C)$

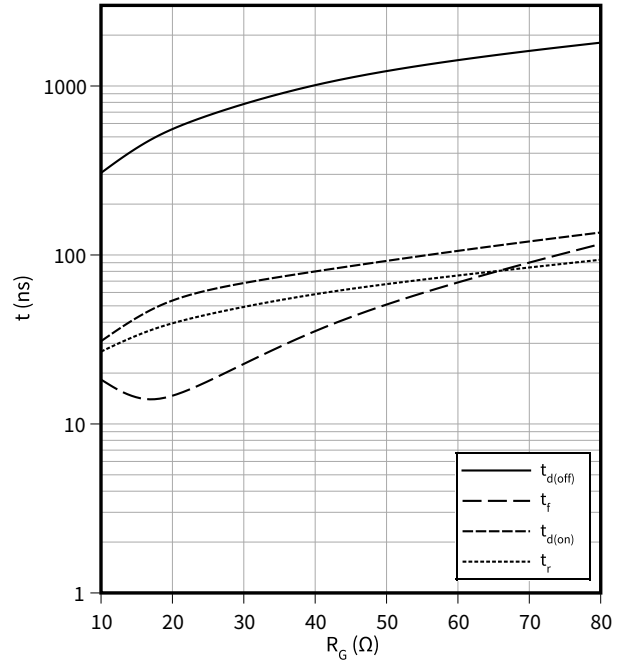
$V_{CC} = 400\text{ V}$ ,  $T_{vj} = 175\text{ °C}$ ,  $V_{GE} = 0/15\text{ V}$ ,  $R_G = 16\text{ }\Omega$



**Typical switching times as a function of gate resistor**

$t = f(R_G)$

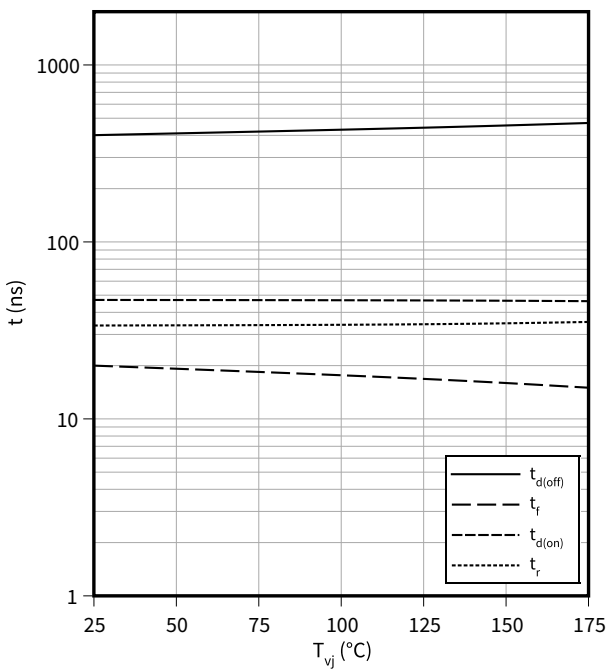
$I_C = 50\text{ A}$ ,  $V_{CC} = 400\text{ V}$ ,  $T_{vj} = 175\text{ °C}$ ,  $V_{GE} = 0/15\text{ V}$



**Typical switching times as a function of junction temperature**

$t = f(T_{vj})$

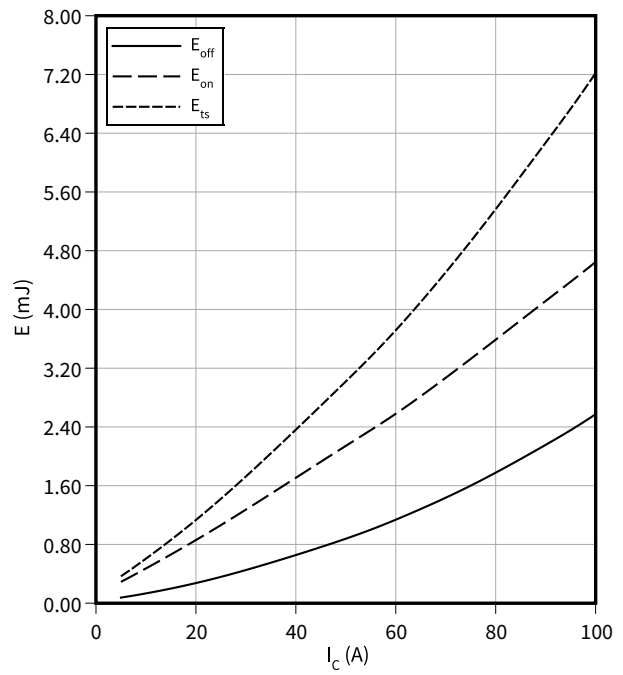
$I_C = 50\text{ A}$ ,  $V_{CC} = 400\text{ V}$ ,  $V_{GE} = 0/15\text{ V}$ ,  $R_G = 16\text{ }\Omega$



**Typical switching energy losses as a function of collector current**

$E = f(I_C)$

$V_{CC} = 400\text{ V}$ ,  $T_{vj} = 175\text{ °C}$ ,  $V_{GE} = 0/15\text{ V}$ ,  $R_G = 16\text{ }\Omega$

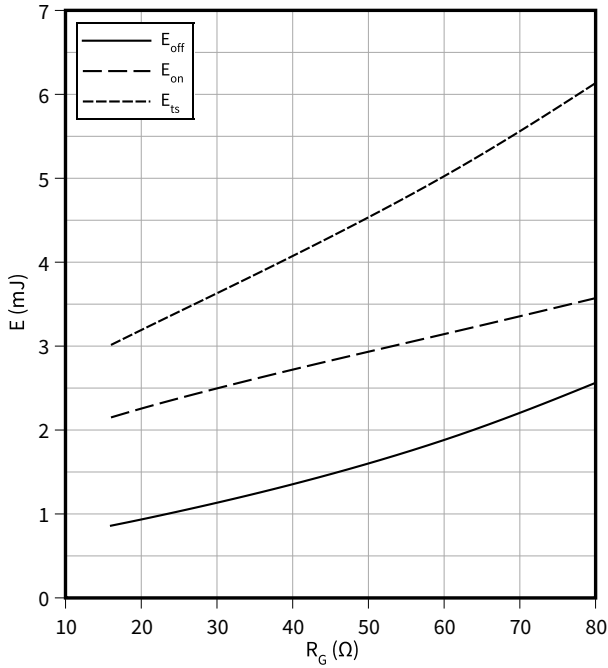


4 Characteristics diagrams

**Typical switching energy losses as a function of gate resistor**

$E = f(R_G)$

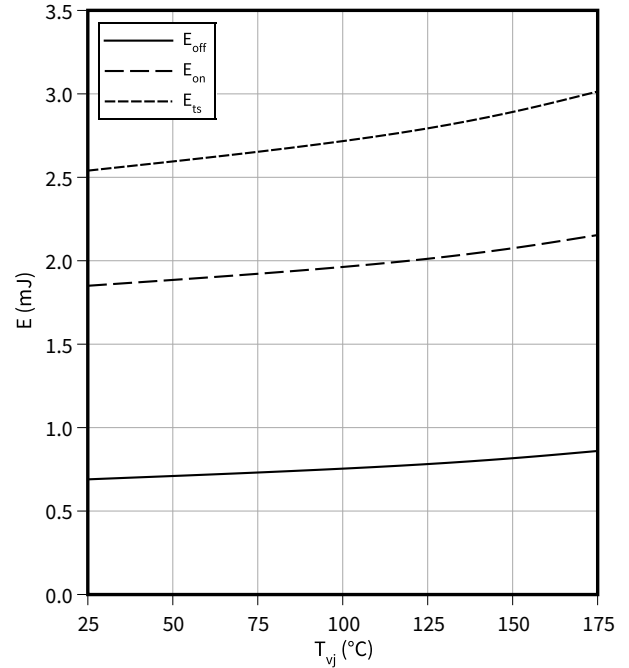
$I_C = 50\text{ A}$ ,  $V_{CC} = 400\text{ V}$ ,  $T_{vj} = 175\text{ °C}$ ,  $V_{GE} = 0/15\text{ V}$



**Typical switching energy losses as a function of junction temperature**

$E = f(T_{vj})$

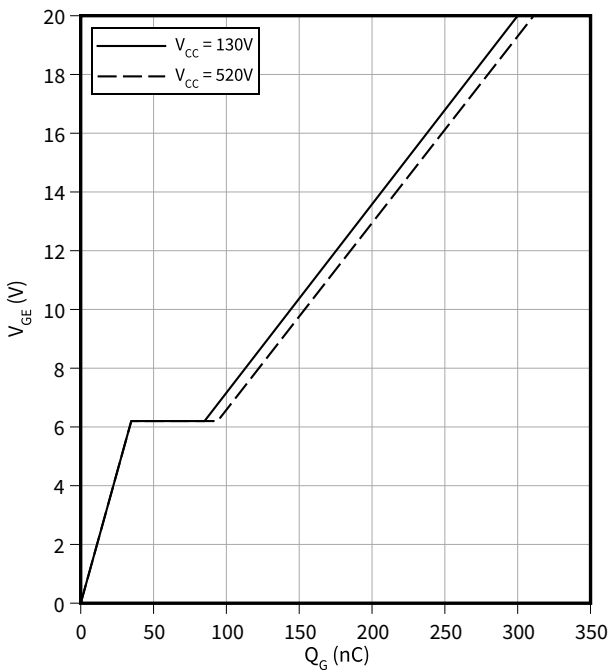
$I_C = 50\text{ A}$ ,  $V_{CC} = 400\text{ V}$ ,  $V_{GE} = 0/15\text{ V}$ ,  $R_G = 16\text{ Ω}$



**Typical gate charge**

$V_{GE} = f(Q_G)$

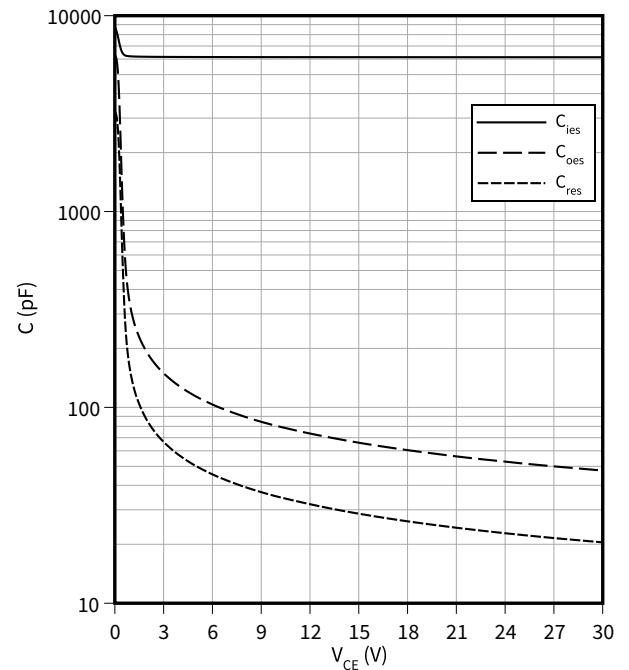
$I_C = 50\text{ A}$



**Typical capacitance as a function of collector-emitter voltage**

$C = f(V_{CE})$

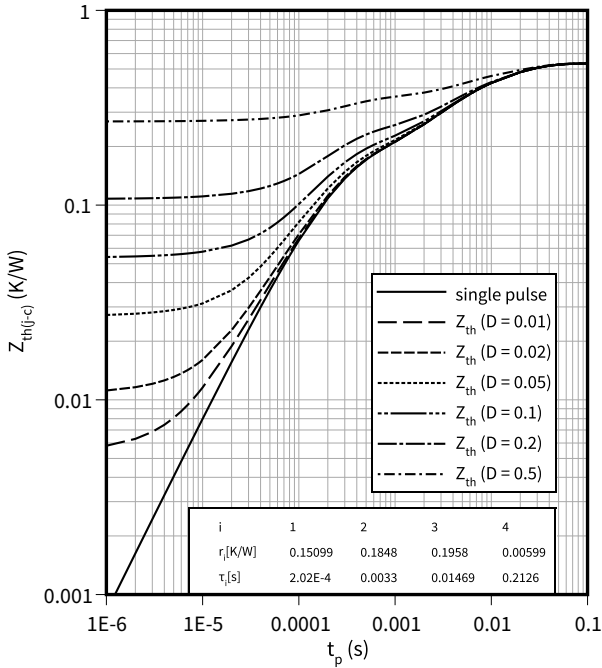
$f = 1000\text{ kHz}$ ,  $V_{GE} = 0\text{ V}$



4 Characteristics diagrams

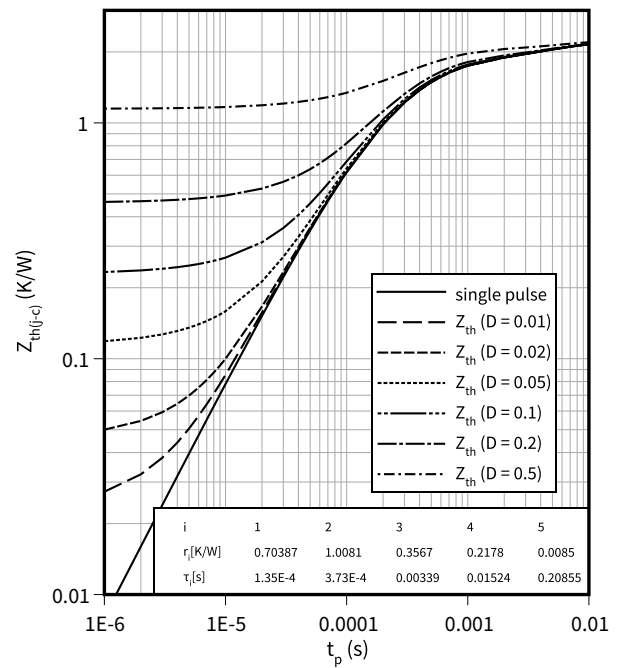
**IGBT transient thermal impedance as a function of pulse width**

$Z_{th(j-c)} = f(t_p)$   
 $D = t_p/T$



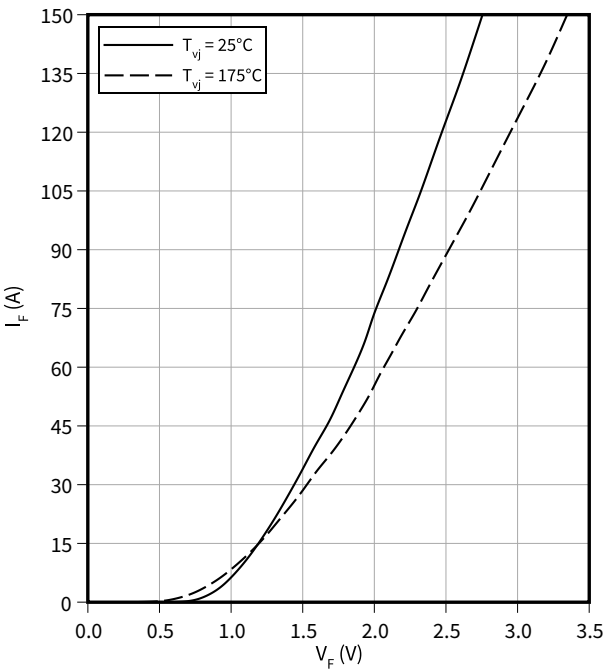
**Diode transient thermal impedance as a function of pulse width**

$Z_{th(j-c)} = f(t_p)$   
 $D = t_p/T$



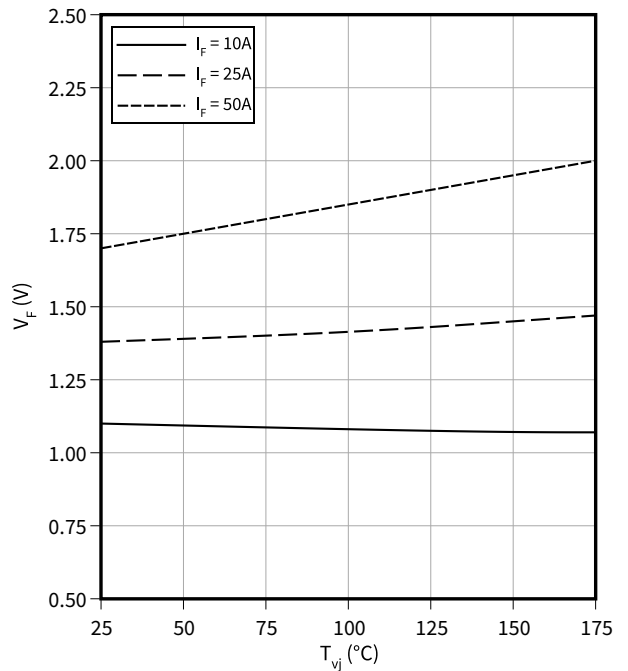
**Typical diode forward current as a function of forward voltage**

$I_F = f(V_F)$



**Typical diode forward voltage as a function of junction temperature**

$V_F = f(T_{vj})$

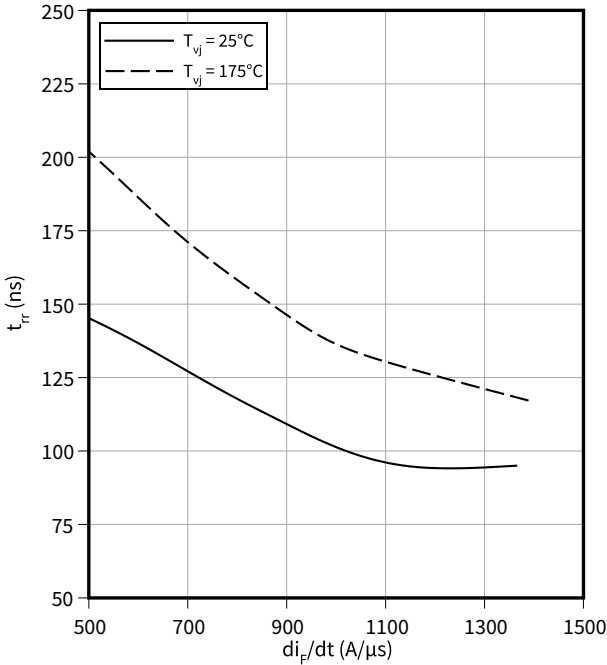


4 Characteristics diagrams

**Typical reverse recovery time as a function of diode current slope**

$$t_{rr} = f(di_F/dt)$$

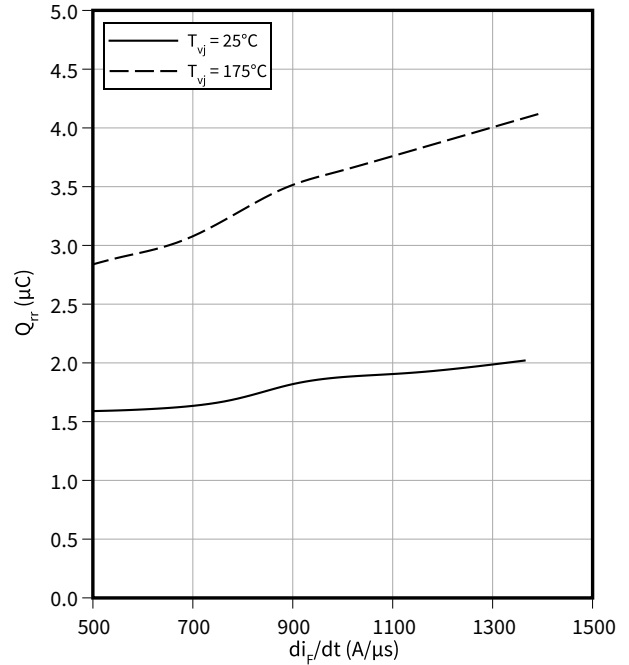
$V_R = 400\text{ V}, I_F = 25\text{ A}$



**Typical reverse recovery charge as a function of diode current slope**

$$Q_{rr} = f(di_F/dt)$$

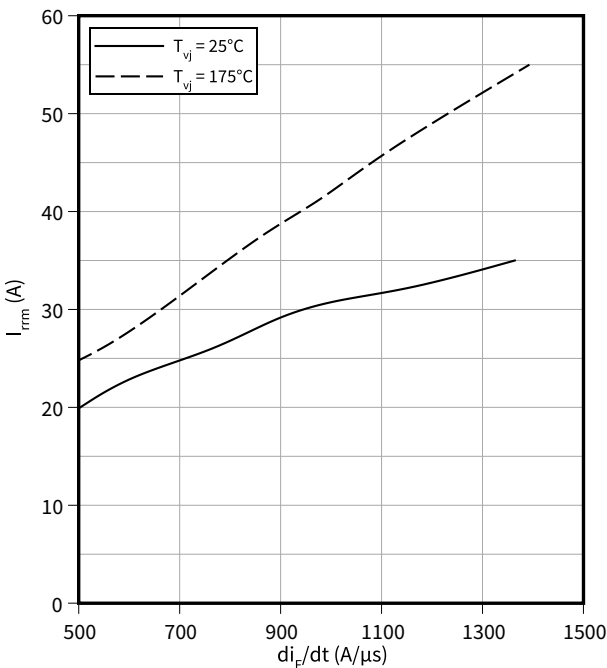
$V_R = 400\text{ V}, I_F = 25\text{ A}$



**Typical reverse recovery current as a function of diode current slope**

$$I_{rrm} = f(di_F/dt)$$

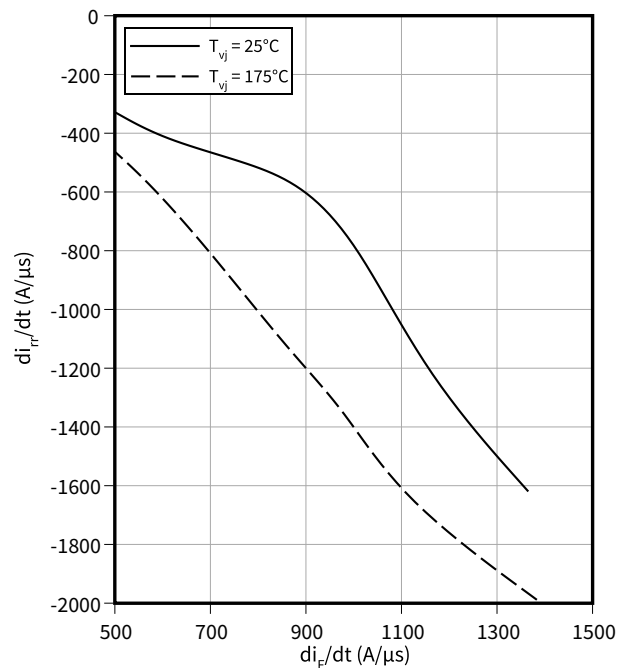
$V_R = 400\text{ V}, I_F = 25\text{ A}$



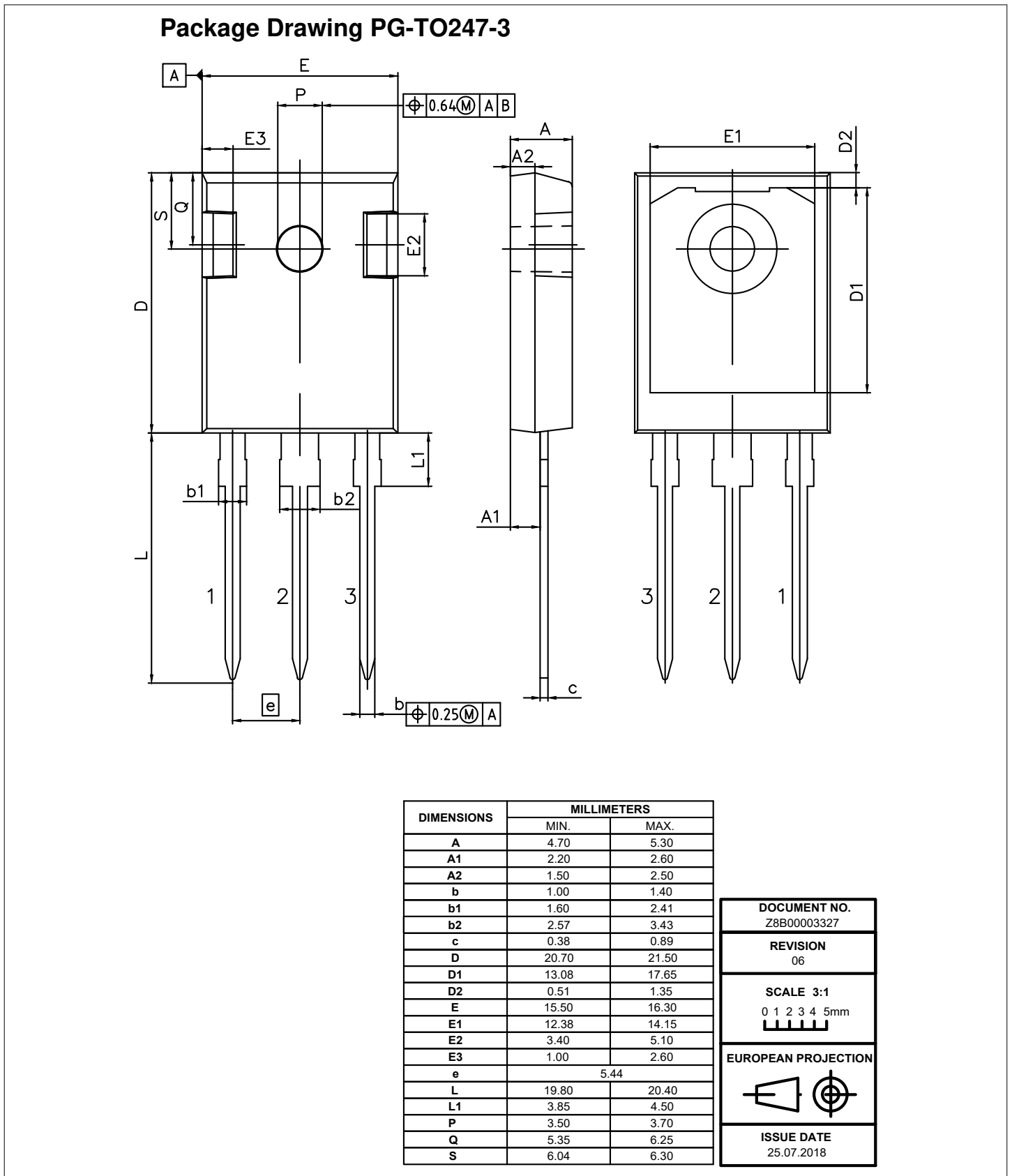
**Typical diode peak rate of fall of reverse recovery current as a function of diode current slope**

$$di_{rr}/dt = f(di_F/dt)$$

$V_R = 400\text{ V}, I_F = 25\text{ A}$

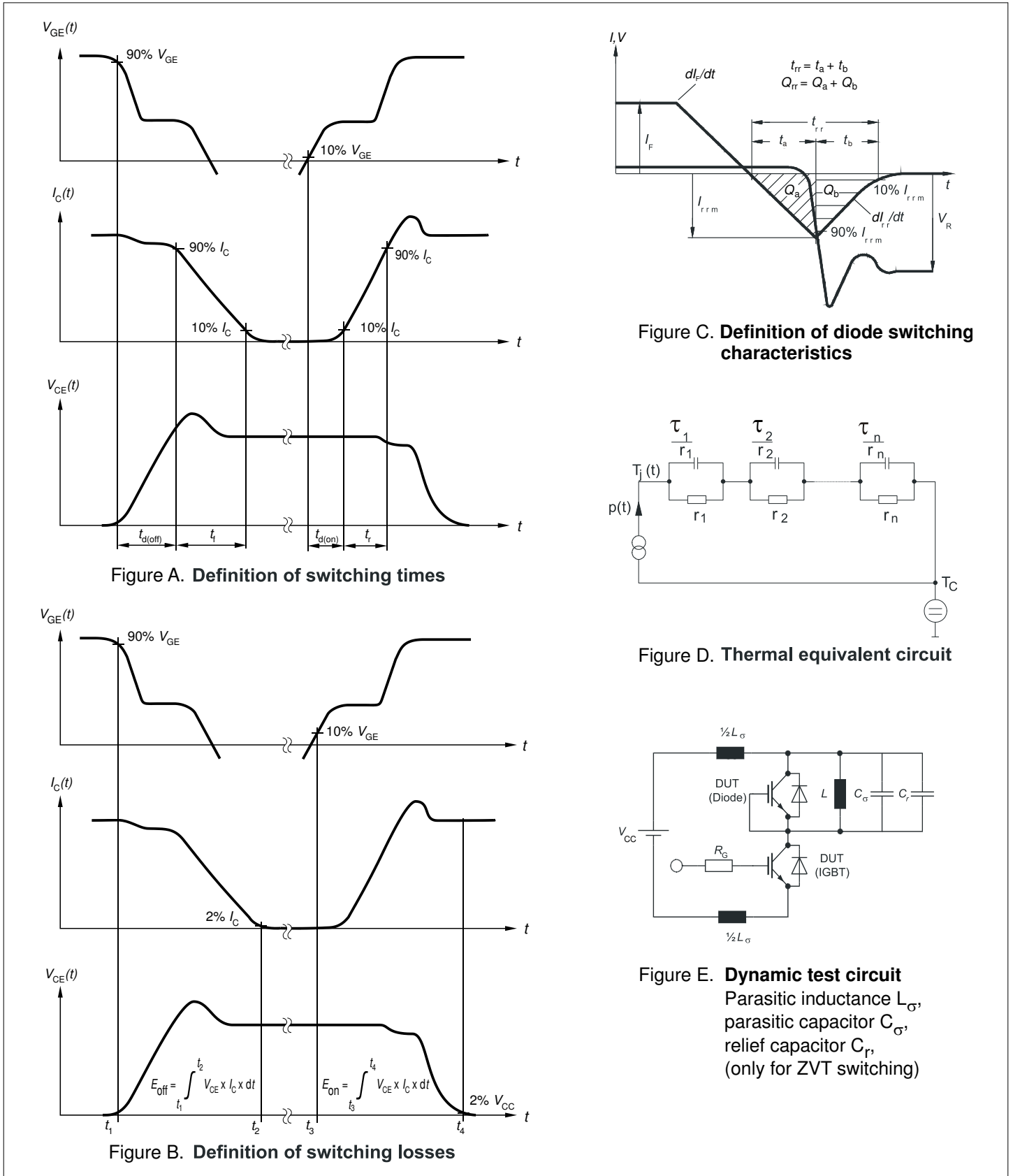


**5 Package outlines**



**Figure 1**

**6 Testing conditions**



**Figure 2**

## Revision history

Document revision	Date of release	Description of changes
V1.1	2014-12-05	Preliminary data sheet
V1.2	2015-03-27	New dynamic parameters and graphs
V1.3	2015-05-13	
V2.1	2015-12-10	Final data sheet
n/a	2020-11-30	Datasheet migrated to a new system with a new layout and new revision number schema: target or preliminary datasheet = 0.xy; final datasheet = 1.xy
1.10	2022-03-08	Added transient gate-emitter voltage
1.20	2022-05-06	Transient gate-emitter voltage $V_{GE}$ added in table “Maximum rated values” of IGBT “Forward bias safe operating area” diagram renamed to “Reverse bias safe operating area”
1.30	2023-06-13	Power dissipation conditions on page 3 updated Editorial changes

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